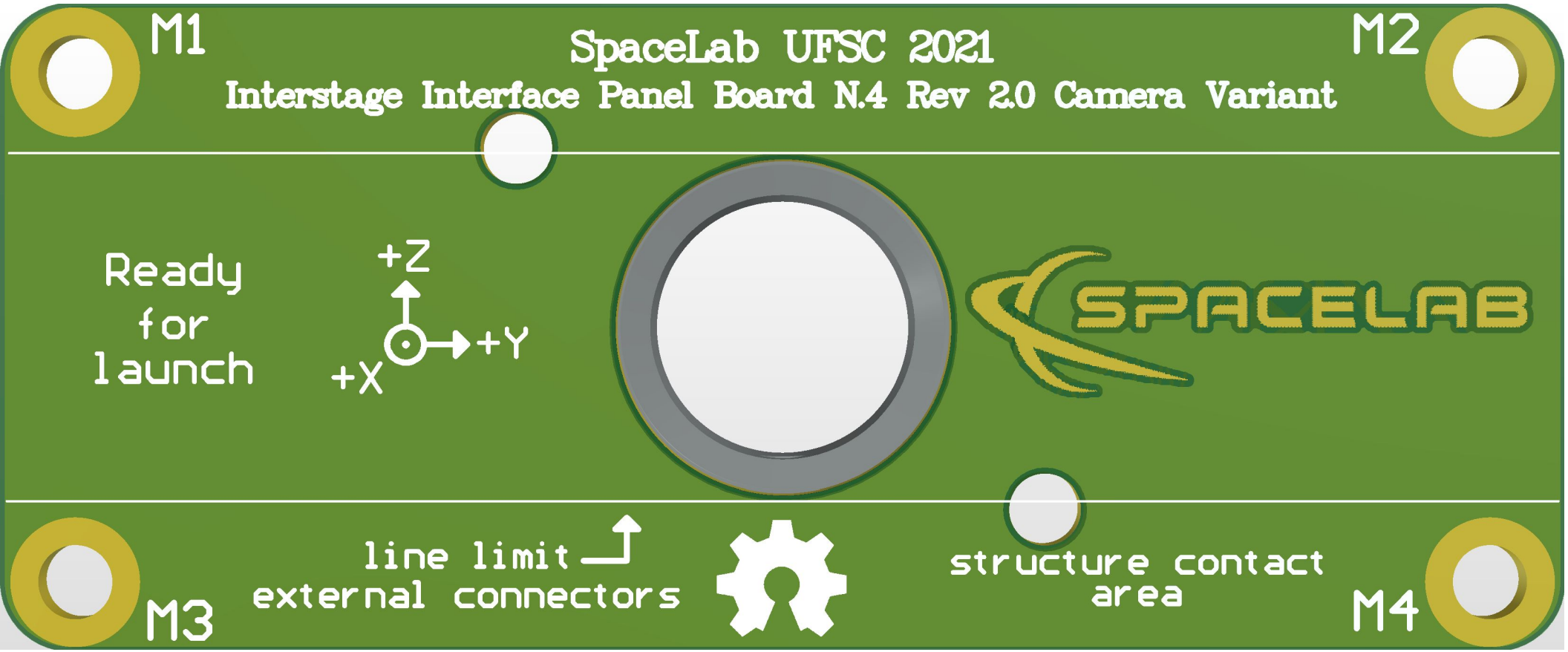
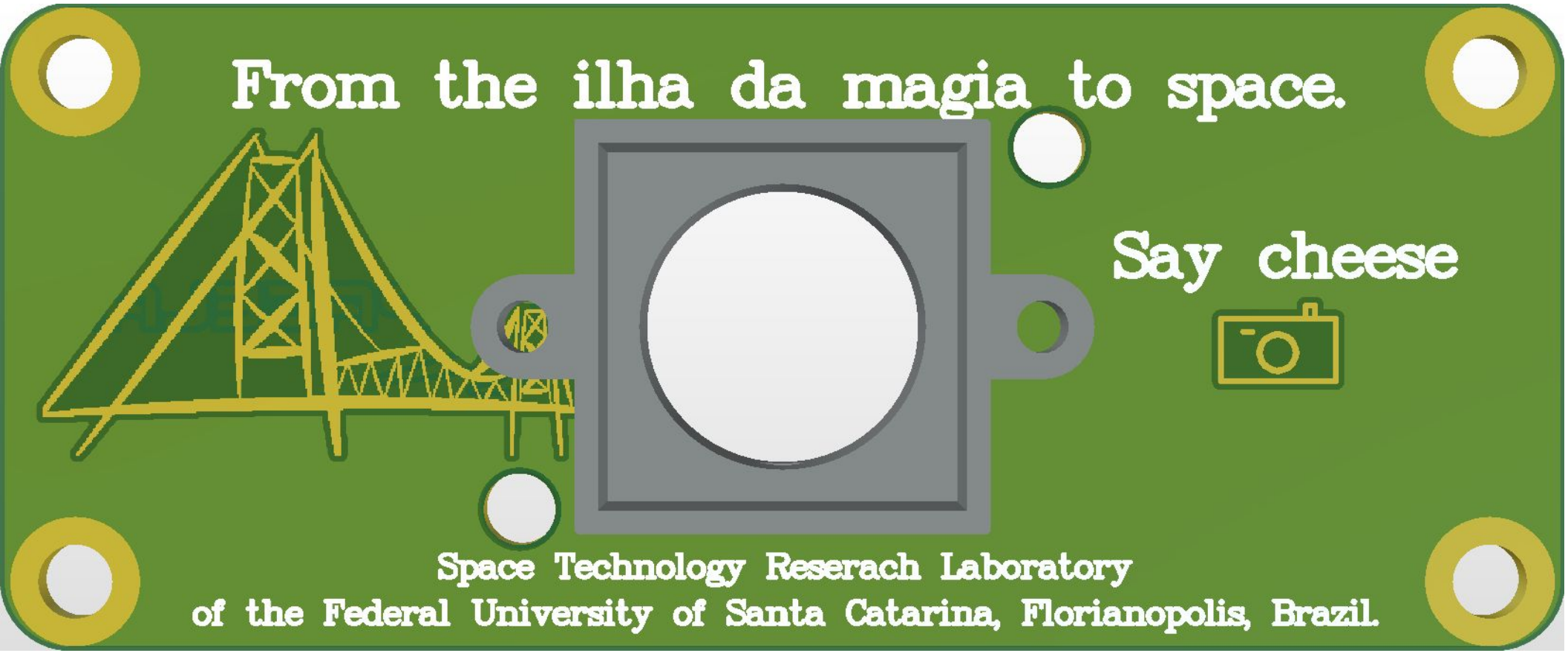

M1
SpaceLab UFSC 2021
Interstage Interface Panel Board N.4 Rev 2.0 Camera Variant
M2
Ready
for
launch
+Z
+Y
+X
SPACELAB
line limit
external connectors
structure contact
area
M3
M4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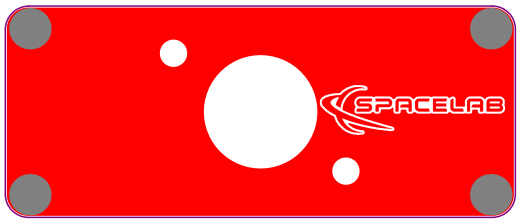
Say cheese
Space Technology Reserach Laboratory
of the Federal University of Santa Catarina, Florianopolis, Brazil.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

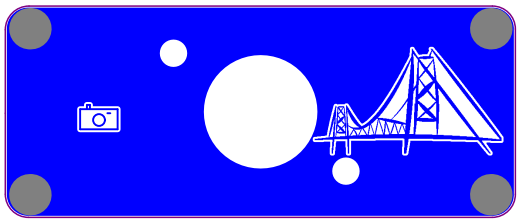


Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4-Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack-up: Standard 2 layer 1.6mm thickness
- Special requirements: None

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Top Layer Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				



Fabrication specifications:

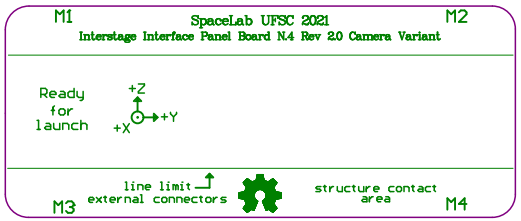
- Copper base: 1oz
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack–up: Standard 2 layer 1.6mm thickness
- Special requirements: None

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Bottom Layer Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4-Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack-up: Standard 2 layer 1.6mm thickness
- Special requirements: None



SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Top Overlay Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack–up: Standard 2 layer 1.6mm thickness
- Special requirements: None

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Space Technology Research Laboratory
of the Federal University of Santa Catarina, Florianopolis, Brasil.

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Bottom Overlay Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4-Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack-up: Standard 2 layer 1.6mm thickness
- Special requirements: None

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Top Paste Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4-Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack-up: Standard 2 layer 1.6mm thickness
- Special requirements: None

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Bottom Paste Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack–up: Standard 2 layer 1.6mm thickness
- Special requirements: None

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Top Solder Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4-Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack-up: Standard 2 layer 1.6mm thickness
- Special requirements: None

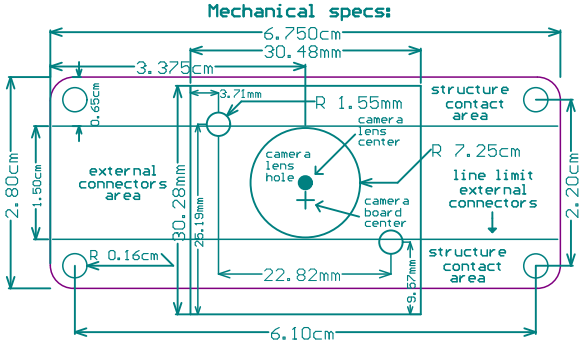
SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Bottom Solder Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4-Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack-up: Standard 2 layer 1.6mm thickness
- Special requirements: None

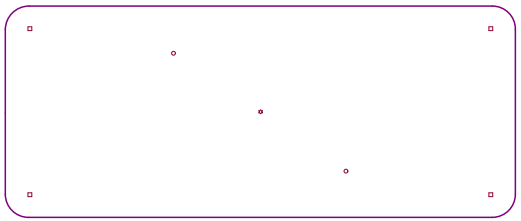
Mechanical specs:



SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Dimensions Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
○	2	3.100mm (122.05mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0h310
□	4	3.200mm (125.98mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c550h320
☼	1	14.500mm (570.87mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0h1450
	7 Total							

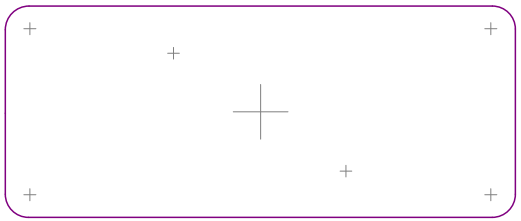


Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4–Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack–up: Standard 2 layer 1.6mm thickness
- Special requirements: None

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Drill Drawing Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.8	
5	Bottom Layer	Copper	0.036mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				



Fabrication specifications:

- Copper base: 1oz
- PCB Material: Prepeg FR4-Standard
- PCB Tickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Stack-up: Standard 2 layer 1.6mm thickness
- Special requirements: None

SpaceLab - Federal University of Santa Catarina		SPACELAB
Project: Interstage Interface Panel Nº4		
Layer: Drill Guide Board Edge		
Designed by: Yan C. de Azeredo		Project Code: IIP4
Date: 7/12/2021	Version: v2.0	Size: A4